

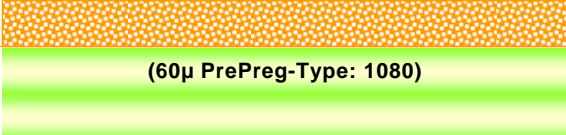







**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**08 106 FR4 35 L10.35 P06**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**08\_106\_FR4\_35\_L10.35\_p06**

Layers	in $\mu$	Material	Build-Up	Assembly		
<b>Layer-1</b>	35 $\mu$	Copper		} <b>A1</b>		
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
<b>Layer-2</b>	35 $\mu$	Copper			} <b>A2</b>	
	100 $\mu$	L-FR4				
<b>Layer-3</b>	35 $\mu$	Copper				} <b>A3</b>
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
<b>Layer-4</b>	35 $\mu$	Copper				
	100 $\mu$	L-FR4				
<b>Layer-5</b>	35 $\mu$	Copper		} <b>A1</b>		
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
<b>Layer-6</b>	35 $\mu$	Copper			} <b>A2</b>	
	100 $\mu$	L-FR4				
<b>Layer-7</b>	35 $\mu$	Copper				} <b>A3</b>
	60 $\mu$	Prepreg				
	60 $\mu$	Prepreg				
<b>Layer-99</b>	35 $\mu$	Copper				

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